BASIC BLADE & BEAM HEADER

(0.50 mm) .0197" PITCH • BTH SERIES

BTH
Mates:
BSH

SPECIFICATIONS

Insulator Material:
Black LCP
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Current Rating:
2.0 A per pin
(2 pins powered)
Operating Temp Range:
-55 °C to +125 °C
Voltage Rating:
175 VAC
Max Cycles:
100

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
Vertical=
(0.10 mm) .004" max (030-090),
(0.15 mm) .006" max (120-150)*
Right-angle=
(0.15 mm) .006" max (030-090)*
*(.004" stencil solution may be available; contact ipg@samtec.com)
Board Stacking:
For applications requiring more than two connectors per board or 90 positions or higher, contact ipg@samtec.com

ALSO AVAILABLE
MOQ Required

30 µ" (0.76 µm) Gold

Edge Mount Capability

8 mm, 11 mm, 16 mm, 19 mm and 22 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.) (11 mm, 16 mm, 19 mm and 22 mm not available with 50 positions)

10 YEAR MFG
WITH 50 µ" GOLD
EXTENDED LIFE PRODUCT
HIGH MATING CYCLES

Note:
Some lengths, styles and options are non-standard, non-returnable.

BTH – NO. OF POSITIONS PER ROW – 01 – PLATING OPTION – D – A – OTHER OPTION

NO. OF POSITIONS PER ROW

–030, –050, –060, –090, –120, –150

PLATING OPTION

–F
= Gold Flash on contact, Matte Tin on tail

–L
= 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail

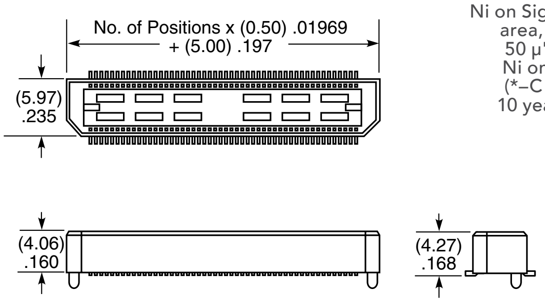
–C*
= Electro-Polished Selective 50 µ" (1.27 µm) min Au over 150 µ" (3.81 µm) Ni on Signal Pins in contact area, Matte Tin over 50 µ" (1.27 µm) min Ni on all solder tails (*–C Plating passes 10 year MFG testing)

OTHER OPTION

–K
= (7.00 mm) .276" DIA Polyimide Film Pick & Place Pad

–TR
= Tape & Reel (120 positions maximum)

–FR
= Full Reel Tape & Reel (must order maximum quantity per reel; contact Samtec for quantity breaks) (120 positions maximum)



MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5.00 mm) .1971"

*Processing conditions will affect mated height.

BTH – NO. OF POSITIONS PER ROW – 01 – PLATING OPTION – D – RA – WT – OTHER OPTION

–030, –060,–090

PLATING OPTION

–F
= Gold Flash on contact, Matte Tin on tail

–L
= 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail

OTHER OPTION

–K
= (7.00 mm) .276" DIA Polyimide Film Pick & Place Pad